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sequentially forming adhesion enhancement layer, copper-bearing metal layer and photoresist layer on substrate, and respectively forming reserved region and removal region by performing exposure and development on photoresist layer using mask plate, wherein reserved region corresponds to pattern forming region, simultaneously processing adhesion enhancement layer, copper-bearing metal layer and photoresist layer in removal region by single wet etching process, to form adhesion enhancement intermediate layer corresponding to adhesion enhancement layer, copper-bearing metal intermediate layer corresponding to copper-bearing metal layer and photoresist layer

simultaneously processing adhesion enhancement intermediate layer, copper-bearing metal intermediate layer and photoresist layer thereon by dry etching process, then stripping off photoresist layer, to form patterned adhesion enhancement layer and patterned copper-bearing metal layer respectively

Fig.1

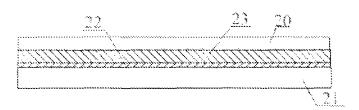


Fig.2

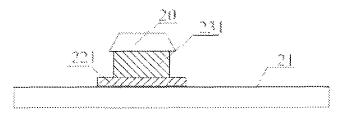


Fig.3